

Serial LINK Code Information(1/2)

S 5 S X X X X X X X - X X X X
 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15

1. System LSI (S)

2. Large Classification : MOS (5)

3. Small Classification

S : SLINK (Serial LINK)

4. Application

- 1 : Ethernet
- 2 : Fiber Channel
- 3 : SONET/SDH
- 4 : InfiniBand
- 5 : Serial ATA
- C : Customization

5~6. Design Rule & Data Trans

- 02 : 0.25um, 2Gbps
- 12 : 0.18um, 2Gbps
- 13 : 0.18um, 3Gbps
- 14 : 0.18um, 4Gbps
- 1A : 0.18um, 10Gbps
- 24 : 0.13um, 4Gbps
- 2A : 0.13um, 10Gbps
- 2D : 0.13um, 40Gbps
- 34 : 0.10um, 4Gbps
- 3A : 0.10um, 10Gbps
- 3D : 0.10um, 40Gbps

7. Method

- A : Multi channel
- D : Dual channel
- F : Four channel
- Q : Quad channel
- S : Single channel
- T : Ten channel

8. Version

- A~Z
- *1st Version → X

9. Interface (Serial / Parallel)

- 4 : 4 bit interface
- 5 : 5 bit interface
- 8 : 8 bit interface
- 1 : 10 bit interface
- 6 : 16 bit interface
- 2 : 20 bit interface

10. Mask Option

" Only Alphabet "

11. " - "

12. Package Type

- | | |
|--------------|------------|
| 1 : TEBGA | B : BGA |
| C : CHIP BIZ | D : DIP |
| E : LQFP | G : CLCC |
| H : LPQ4 | J : ELP |
| K : SBGA | L : CERDIP |
| M : QFPH | T : TQFP |
| W : WAFER | Y : FBGA |
| Z : STBGA | |

13. Reserved

14. Packing

- | | |
|------------------------------------|-----------------|
| B : Tube | U : Bulk |
| R : Tray | T : Tape & Reel |
| S : Tape & Reel Reverse | C : Chip Biz |
| D : Chip Biz (3 Inch tray) | |
| E : Chip Biz (4 Inch tray) | |
| F : Chip Biz (Reverse) | |
| W : WF Biz Draft Wafer | |
| X : WF Biz Full Cutting | |
| 3 : Tape & Reel (Halogen-Free PKG) | |
| 4 : Tray (Halogen-Free PKG) | |
| 5 : Tube (Halogen-Free PKG) | |
| 7 : Tape & Reel (Lead-Free PKG) | |
| 8 : Tray (Lead-Free PKG) | |
| 9 : Tube (Lead-Free PKG) | |

Serial LINK Code Information(2/2)

<u>S</u>	<u>5</u>	<u>S</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	-	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>
1	2	3	4	5	6	7	8	9	10	11	12	13	14	15

15. Customer

- 0 : None
- 1 : Bonding Option 1
- 2 : Bonding Option 2
- 3 : Bonding Option 3
- 4 : Bonding Option 4
- 5 : Bonding Option 5
- 6 : Bonding Option 6
- 7 : Bonding Option 7
- 8 : Bonding Option 8
- 9 : Bonding Option 9
- A : Special Marking 1
- B : Special Marking 2
- C : Special Marking 3
- D : Special Marking 4
- E : Special Marking 5
- F : Special Marking 6
- K : Reliability Test
- L : No Logo
- M : No Marking
- N : ANAM Assembly
- Q : Bonding Option 10
- R : Bonding Option 11
- S : Bonding Option 12
- T : Bonding Option 13
- U : Bonding Option 14
- Z : Customer Option z